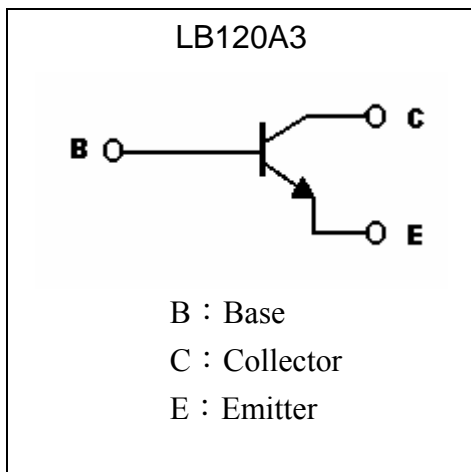
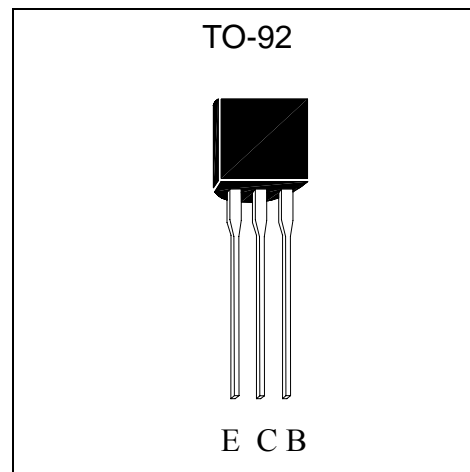


General Purpose NPN Epitaxial Planar Transistor

LB120A3

Features

- Low collector saturation voltage
- High breakdown voltage, $V_{CEO}=400V$ (min.)
- Pb-free package

Symbol

Outline

Absolute Maximum Ratings ($T_a=25^\circ C$)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V_{CBO}	600	V
Collector-Emitter Voltage	V_{CEO}	400	V
Emitter-Base Voltage	V_{EBO}	9	V
Collector Current (DC)	I_C	0.5	A
Power Dissipation	P_D	1	W
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	125	$^\circ C/W$
Junction Temperature	T_j	150	$^\circ C$
Storage Temperature	T_{stg}	-55~+150	$^\circ C$

 Note : Pulse test, $P_w \leq 10ms$, Duty $\leq 50\%$.



Characteristics (Ta=25°C)

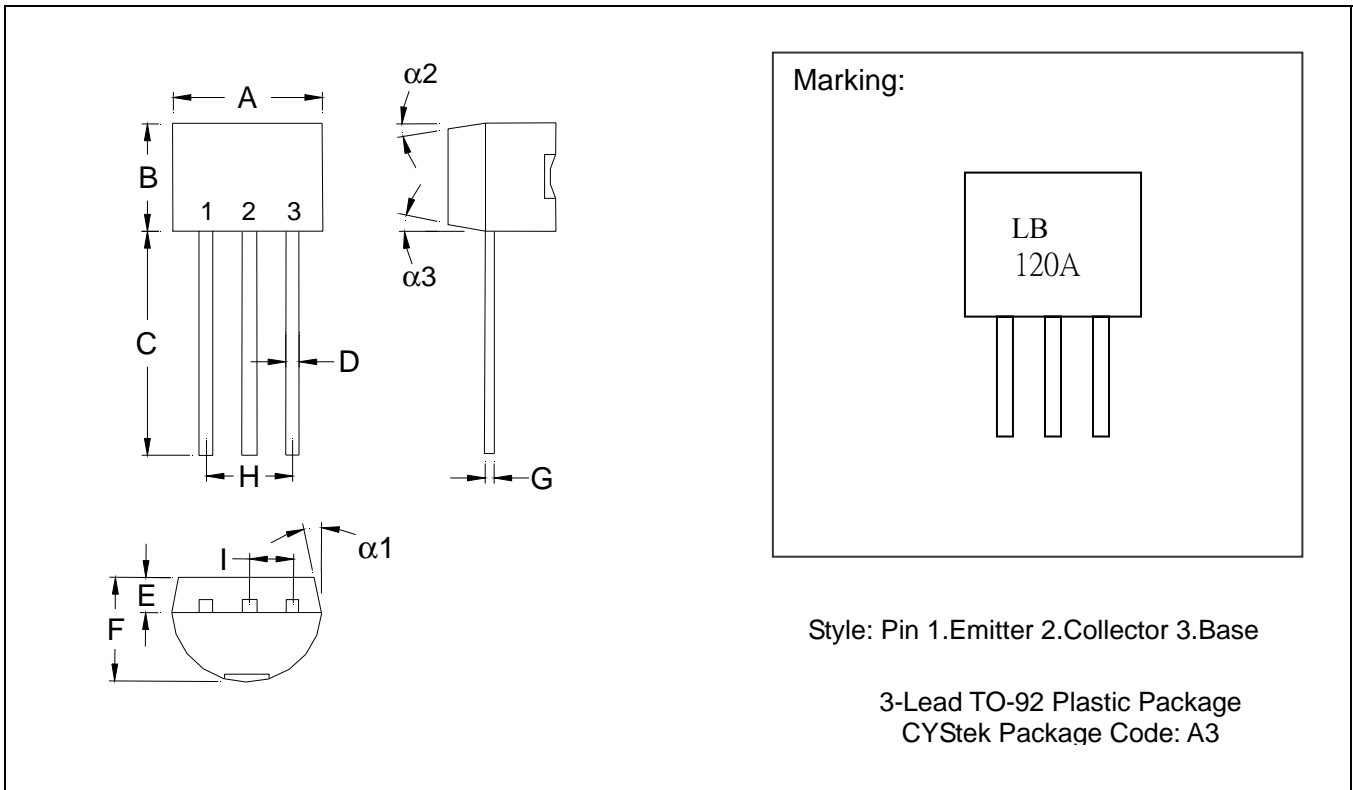
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV_{CBO}	600	-	-	V	$I_C=100\mu A$
BV_{CEO}	400	-	-	V	$I_C=1mA$
BV_{EBO}	9	-	-	V	$I_E=10\mu A$
I_{CBO}	-	-	15	μA	$V_{CB}=600V, I_E=0$
I_{EBO}	-	-	100	nA	$V_{EB}=8V, I_C=0$
* $V_{CE(SAT)}$	-	-	0.3	V	$I_C=50mA, I_B=10mA$
* $V_{CE(SAT)}$	-	-	0.5	V	$I_C=200mA, I_B=40mA$
* h_{FE}	10	-	40	-	$V_{CE}=20V, I_C=20mA$
tf	-	-	0.5	μs	$V_{CE}=100V, I_C=300mA, I_{B1}=-I_{B2}=100mA$
ts	-	-	2.5		

*Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$

Classification Of h_{FE}

Rank	A	B	C	D	E	F
Range	10~15	15~20	20~25	25~30	30~35	35~40

TO-92 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	$\alpha 1$	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	$\alpha 2$	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	$\alpha 3$	-	*2°	-	*2°

Notes: 1. Controlling dimension: millimeters.
 2. Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3. If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: KFC ; pure tin plated
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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